

Soldering Temperature Profiles

Infrared reflow

Recommends the reflow method using far- and middle-infrared radiation plus panel heater. Figure 1 shows an example of recommended temperature profile for infrared reflow.

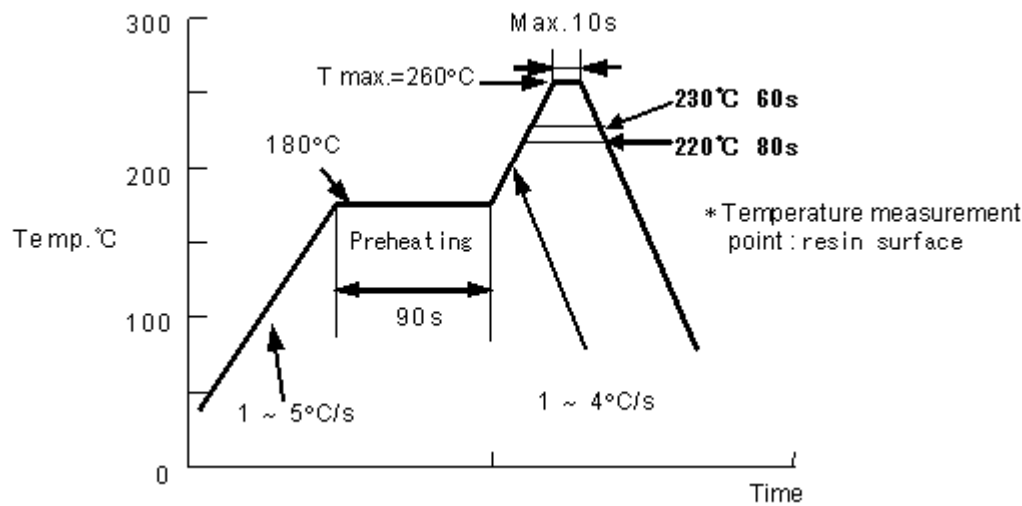


Figure1 Recommended temperature profile of infrared reflow

Solder dipping

Solder dipping gives larger thermal stress to packages compared to infrared reflow. Preheating is indispensable to relax the thermal stress. Figure 2 shows an example of recommended temperature profile of solder dipping.

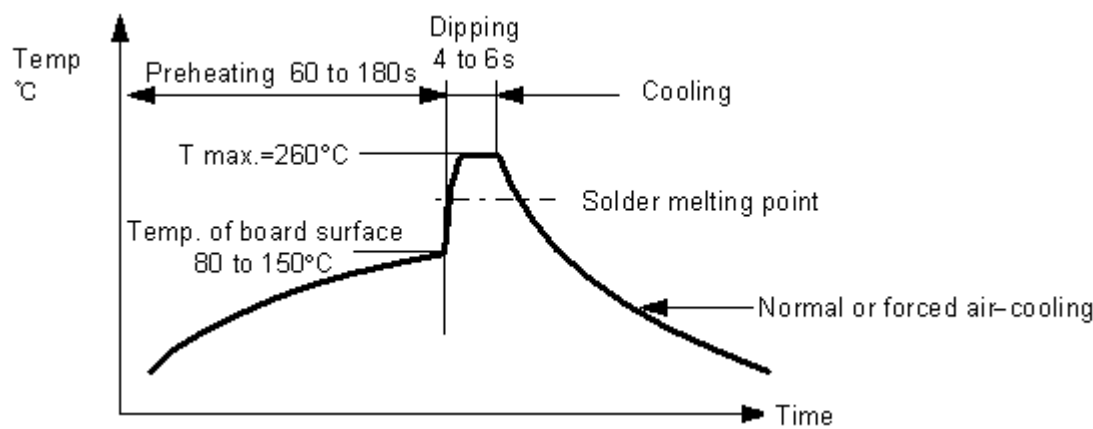


Figure 2 Recommended temperature profile of solder dipping